	CONNECTING CS INDUSTRIES® International and Pan	PC, Bannockb	urn, Illinois. A	All rights reserved u ntions.	nder both	This docume level parts, t	ent is a declara he declaration	tion of t encomp	the substances passes all lowe	within the er level mat	manufactur terials for wl	er listed it hich the m	em. Note: i anufacturei	f the item is an as has engineering	sembly with low responsibility.	
752-21.1					Form Type Distribute						eous Materia	rials and Mfg Information				
upplie	r Information															
Company name* Com				Company unique ID			Unique ID Authority					Response Date*				
nsemi												2025-07-01				
ontact N	lame	Title - Contact				Phone - Contact*					Email - Contact*					
Product-	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
uthorize	ed Representative*		Title - Representative				Phone - Representative*				Email - Representative*					
roduct-	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item   H11G1T						Effective Date	te Version Manufacturing Site		ring Site	V	Veight*	UOM	Unit Type		
							2025-07-01 THH			449.722		mg	Each			
Ianufa	cturing Proccess Informat	ion														
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 M		-STD-020 MS	L Rating	Peak Process Body Tempera		ture Max Time at Peak Te		Temperat	are Numb	er of Reflow Cyc	eles		
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30 seco		second	is 3						
omments	8															
or more	information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	nantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl putyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted								
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.												
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Coupling Gel	0.4	mg	Supplier	Dimethyl Cyclosiloxanes	69430-24-6		0.04	mg
			Supplier	Trimethoxy(methyl)silane (C4H12O3Si)	1185-55-3		0.36	mg
Die	5.13	mg	Supplier	Silicon (Si)	7440-21-3		5.13	mg
Die Attach	0.3	mg	Supplier	Silver (Ag)	7440-22-4		0.225	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.075	mg
Lead Frame	108.322	mg	Supplier	Silver (Ag)	7440-22-4		0.68	mg
			Supplier	Zinc (Zn)	7440-66-6		0.13	mg
			Supplier	Iron (Fe)	7439-89-6		2.48	mg
			Supplier	Copper (Cu)	7440-50-8		105	mg
			Supplier	Phosphorus (P)	7723-14-0		0.032	mg
Mold Compound-White	327.22	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		81.805	mg
			В	Brominated Bisphenol A Diglycidyl Ether	40039-93-8		9.8166	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		44.1747	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		9.8166	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		163.61	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		17.9971	mg
Plating	6.7	mg	Supplier	Tin (Sn)	7440-31-5		6.7	mg
Wire Bond - Au	1.65	mg	Supplier	Gold (Au)	7440-57-5		1.65	mg